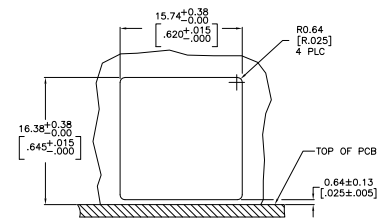
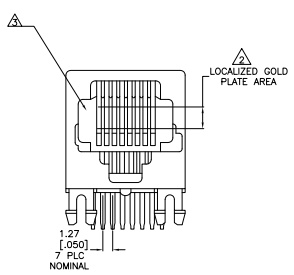
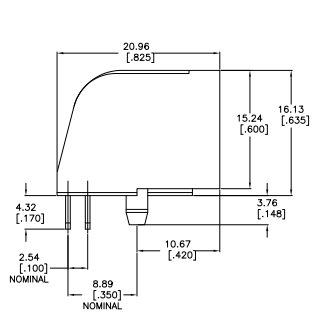


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REV	DATE	DESCRIPTION	BY	APP
AA	00			
B	02-07-2009			

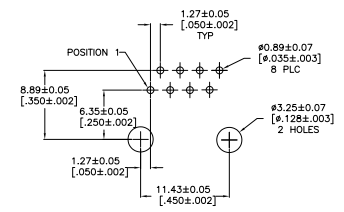
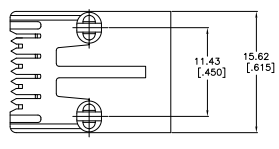


RECOMMENDED PANEL CUTOUT

1. MATERIAL: HOUSING PBT POLYESTER, COLOR: BLACK.
 TERMINAL—0.35 [0.014] THICK PHOS-BRONZE
 PLATED WITH 1.27µm [0.00050] MINIMUM THICK HARD
 GOLD IN LOCALIZED GOLD PLATE AREA AND
 3.81µm [0.00150] MINIMUM THICK MATTE TIN IN SOLDER
 AREA OVER 1.27µm [0.00050] MINIMUM THICK NICKEL
 UNDERPLATE.

△ CAVITY CONFORMS TO FCC RULES AND
 REGULATIONS PART 68 AND REA BULLETIN
 345-61, PE-76 SPECIFICATION FOR MODULAR
 TELEPHONE HARDWARE.

3. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS
 OTHERWISE SPECIFIED.



RECOMMENDED PRINTED CIRCUIT BOARD
 LAYOUT
 COMPONENT SIDE SHOWN

5554517-1
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DESIGNED BY	JAM/000	DATE	06/02/07
DRAWN BY		REVISIONS	108-1163	MODULAR JACK ASSEMBLY, SIDE ENTRY, 8 POSITION, KEYED, FLANGELESS, WITHOUT PANG, STOPS	
CHECKED BY		REVISED BY	114-2048	DATE	02/07/09
APPROVED BY		CUSTOMER DRAWING		DATE	02/07/09
SEE NOTE 1		SEE NOTE 1		SIZE	A1
				SHEET	1 OF 1